

### **DESCRIPTION**

The SPP9433W is the P-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology.

This high density process is especially tailored to minimize on-state resistance.

These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other battery powered circuits, and low in-line power loss are needed in a very small outline surface mount package.

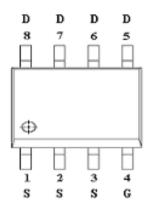
#### **FEATURES**

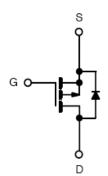
- -30V/-6A, RDS(ON)=  $42m\Omega$ @VGS=-10V
- $-30V/-3 \text{ A,RDS(ON)} = 78m\Omega@VGS = -4.5V$
- ◆ Super high density cell design for extremely low RDS (ON)
- Exceptional on-resistance and maximum DC current capability
- ◆ SOP-8P package design

### **APPLICATIONS**

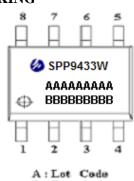
- Power Management in Note book
- Portable Equipment
- Battery Powered System
- DC/DC Converter
- Load Switch
- LCD Display inverter

### PIN CONFIGURATION(SOP - 8P)





#### **PART MARKING**



B : Date Code

PIN DESCRIPTION						
Pin	Symbol	Description				
1	S	Source				
2	S	Source				
3	S	Source				
4	G	Gate				
5	D	Drain				
6	D	Drain				
7	D	Drain				
8	D	Drain				

## **ORDERING INFORMATION**

Part Number	Package Part Marking	
SPP9433WS8RGB	SOP- 8P	SPP9433W

<sup>※</sup> SPP9433WS8RGB: 13" Tape Reel; Pb − Free; Halogen - Free

## ABSOULTE MAXIMUM RATINGS

(TA=25°C Unless otherwise noted)

Parameter	Symbol	Typical	Unit	
Drain-Source Voltage		Vdss	-30	V
Gate –Source Voltage		VGSS	±20	V
Continuous Drain Current/Tr-150°C)	TA=25°C	In	-6	Α.
Continuous Drain Current(TJ=150°C)	Ta=70°C	- Id	-4	A
Pulsed Drain Current		Ірм	-12	A
Continuous Source Current(Diode Conduction)		Is	-6	A
Power Dissipation	TA=25°C	PD	2.08	W
Operating Junction Temperature		Тл	-55/150	$^{\circ}\! \mathbb{C}$
Storage Temperature Range		Tstg	-55/150	$^{\circ}\! \mathbb{C}$
Thermal Resistance-Junction to Ambient		R <sub>θ</sub> JA	60	°C/W

## **ELECTRICAL CHARACTERISTICS**

(Ta=25°C Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Тур	Max.	Unit	
Static	•		•	•			
Drain-Source Breakdown Voltage	V(BR)DSS	VGS=0V,ID=-250uA	-30			V	
Gate Threshold Voltage	VGS(th)	VDS=VGS,ID=-250uA	-1.0		-2.5	]	
Gate Leakage Current	Igss	V <sub>DS</sub> =0V,V <sub>GS</sub> =±20V			±100	nA	
Zero Gate Voltage Drain Current	IDSS	V <sub>DS</sub> =-24V,V <sub>GS</sub> =0V V <sub>DS</sub> =-24V,V <sub>GS</sub> =0V T <sub>J</sub> =55°C			-1 -5	uA	
On-State Drain Current	ID(on)	V <sub>DS</sub> ≤-5V,V <sub>GS</sub> =-10V	-6			A	
Drain-Source On-Resistance	RDS(on)	V <sub>GS</sub> =- 10V,I <sub>D</sub> =-6A V <sub>GS</sub> =- 4.5V,I <sub>D</sub> =-3A		0.035	0.042 0.078	Ω	
Forward Transconductance	gfs	V <sub>DS</sub> =-10.0V,I <sub>D</sub> =-6A		6		S	
Diode Forward Voltage	Vsd	Is=-6A,VGS=0V			-1.2	V	
Dynamic							
Total Gate Charge	Qg			6.4			
Gate-Source Charge	Qgs	V <sub>DS</sub> =-20V, V <sub>GS</sub> =-4.5V I <sub>D</sub> =-6A		2.7		nC	
Gate-Drain Charge	Qgd	-10 -071		3.1			
Input Capacitance	Ciss			650		pF	
Output Capacitance	Coss	V <sub>DS</sub> =-24V,V <sub>GS</sub> =0V f=1MHz		270			
Reverse Transfer Capacitance	Crss	1 1141117		104			
T. O T'	td(on)			9		ns	
Turn-On Time	tr	VDD=-12V, ID=-5.0A,		16			
T. OMT.	td(off)	$V_{GEN}=-10V$ $R_{G}=3.3\Omega$		21			
Turn-Off Time	tf			22			



## **P-Channel Enhancement Mode MOSFET**

## TYPICAL CHARACTERISTICS

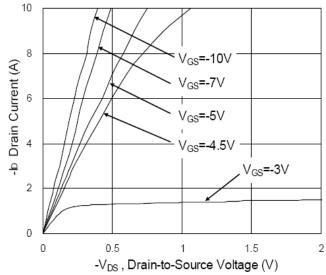


Fig. 1 Typical Output Characteristics

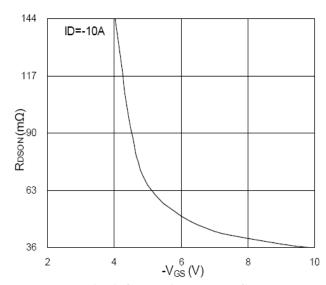


Fig. 2 On-Resistance vs. Gate Voltage

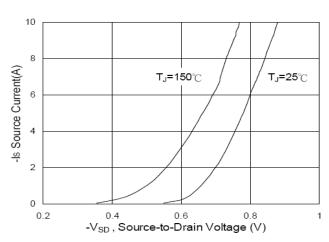


Fig. 3 Forward characteristics of Diodes

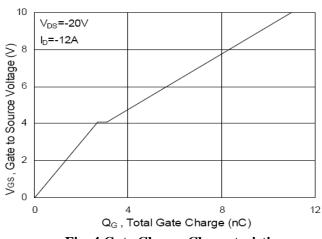


Fig. 4 Gate Charge Characteristics

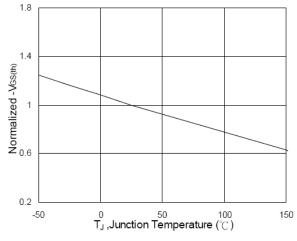


Fig. 5 Vgs vs. Junction Temperature

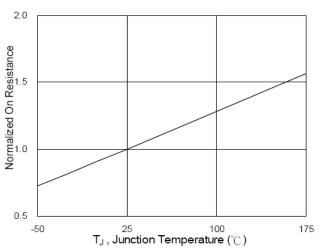
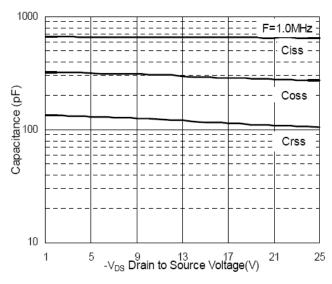


Fig. 6 On-Resistance vs Junction Temp

# **P-Channel Enhancement Mode MOSFET**

### TYPICAL CHARACTERISTICS



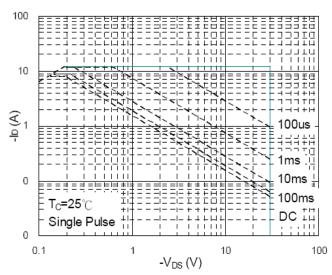


Fig. 7 Typical Capacitance Characteristics

Fig. 8 Maximum Safe Operation Area

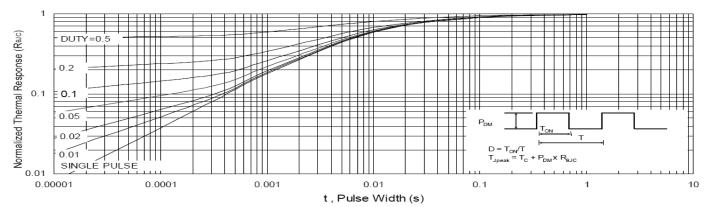


Fig. 9 Effective Transient Thermal Impedance

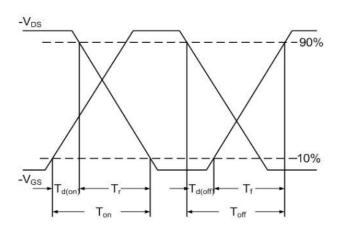


Fig. 10 Switching Time Waveform

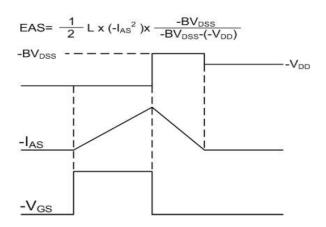
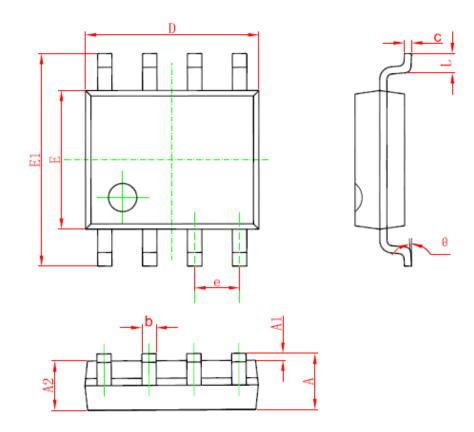


Fig. 11 Unclamped Inductive Waveform



## **SOP- 8 PACKAGE OUTLINE**



611	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
А	1. 350	1. 750	0.053	0.069	
A1	0. 100	0. 250	0.004	0. 010	
A2	1. 350	1. 550	0.053	0.061	
b	0. 330	0. 510	0.013	0. 020	
С	0. 170	0. 250	0.006	0.010	
D	4. 700	5. 100	0. 185	0. 200	
Е	3.800	4. 000	0. 150	0. 157	
E1	5. 800	6. 200	0. 228	0. 244	
е	1. 270 (BSC)		0. 050 (BSC)		
L	0. 400	1. 270	0.016	0.050	
θ	0°	8°	0°	8°	

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